

Connector for microSD™ Card (Header Type)

SCHD Series



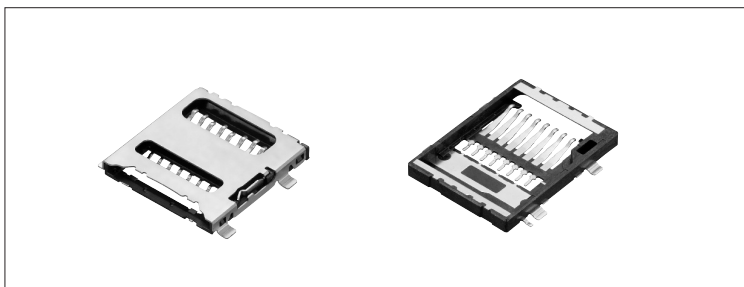
Low-profile provides improved flexibility in set design.

For SD Memory Card

For microSD™ Card

For SIM Card 8pins

For Memory Stick Micro™



Combine Type

For W-SIM

Typical Specifications

Items		Specifications
Structure	Applicable media	microSD™ Card
	Mounting type	Surface mounting type
	Mounting style	Standard mount
	Media ejection structure	Manual insertion/removal
Performance	Operating temperature range	-20°C to +70°C
	Voltage proof	250V AC 1minute
	Insulation resistance (Initial)	1,000MΩ min.
	Contact resistance (Initial)	100mΩ max.
	Insertion and removal cycle	10,000cycles

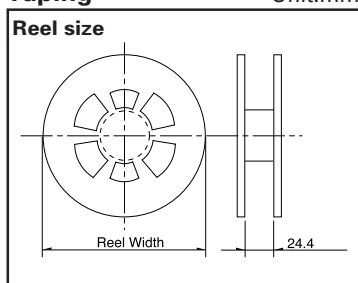
Product Line

Media ejection structure	Mounting system	Stand-off (mm)	Packing system	Product No.	Drawing No.
Manual insertion/removal	Standard mount	0	Taping	SCHD1A0101	1
				SCHD3A0100	2

Packing Specifications

Taping

Unit:mm



Product No.	Number of packages (pcs.)			Reel width (mm)	Tape width (mm)	Export package measurements (mm)
	1 reel	1 case /Japan	1 case /export packing			
SCHD1A0101	1,400	4,200	8,400	330	24	353×353×249
SCHD3A0100	2,000	6,000	12,000	380		403×403×249

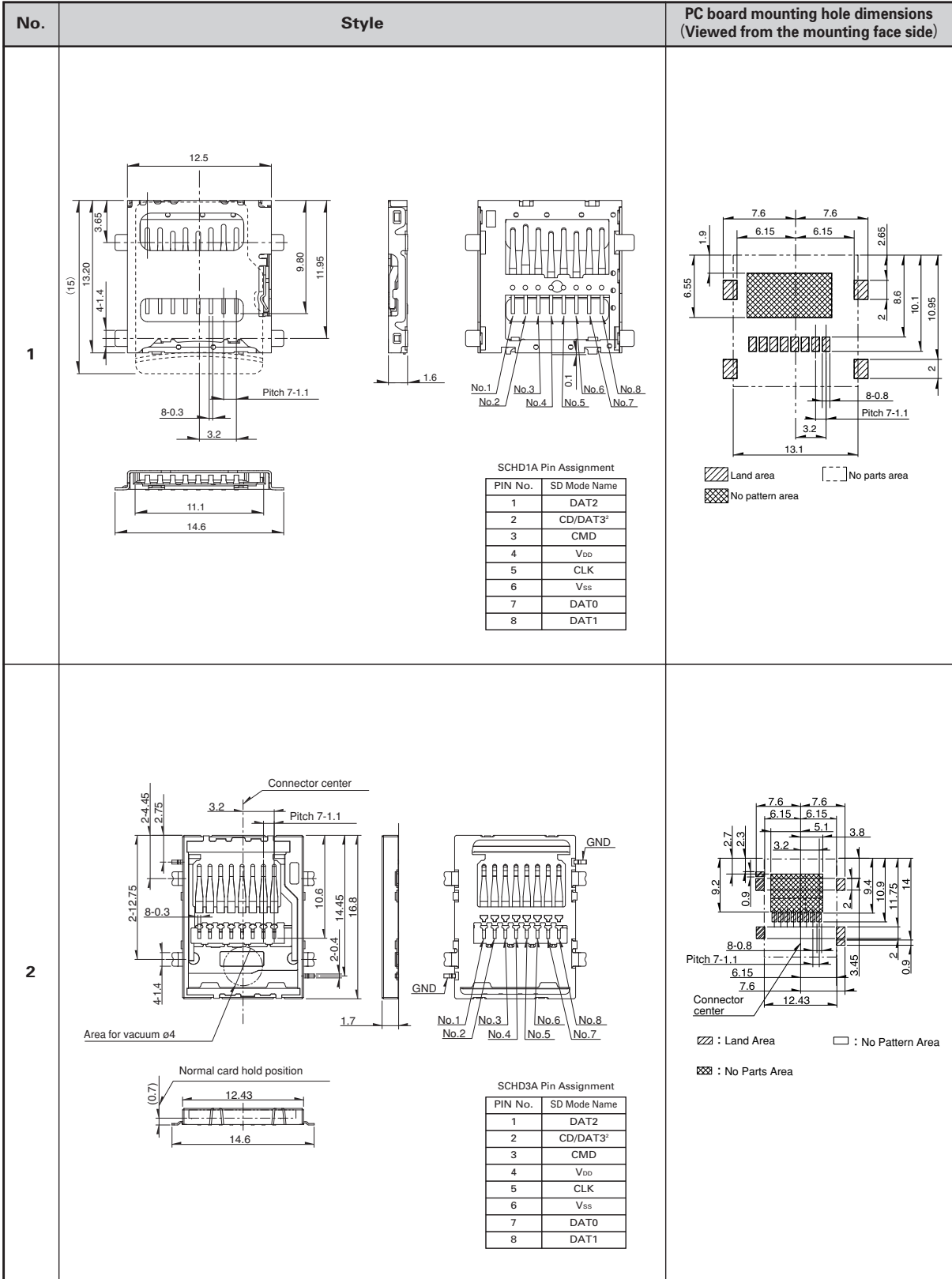
Note

Please place purchase orders per minimum order unit N (integer).

Refer to P.558 for soldering conditions.

Dimensions

Unit:mm



For SD Memory Card

For microSD™ Card

For SIM Card 8pins







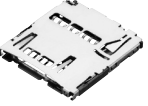







For Memory Stick Micro™

Combine Type

For W-SIM

List of Varieties

- For SD Memory Card
- For microSD™ Card
- For SIM Card 8pins
- For Memory Stick Micro™
- Combine Type
- For W-SIM

Applicable media	Product No.	Photo	Media ejection structure	Mounting style	Features	Stand-off (mm)	Auto motive use	Page
SD Memory Card Multi-MediaCard™	SCDA9A0400		Push-push type	Standard mount	Inner tail Card eject stroke 5mm	0	—	527
	SCDA8A0201				Inner tail Card eject stroke 8mm			
	SCDA7A0101				Card eject stroke 8mm	1.5	○	
	SCDA7A0200			1.8				
	SCDAAA0100			Reverse mount	Outer tail	0	—	
	SCDAAA0601					1.8		
	microSD™ Card	SCHA4B0100			Manual insertion/removal	Standard mount	With switch	
SCHA4B0400			With switches and fly-out protection.	—				
SCHA5B0200			Reverse mount	With switch		○		
SCHB1A0205			Manual insertion/removal	Standard mount	Hinge cover type Without switch	0	—	535
SCHB1B0100					Hinge cover type With switch			
SCHD1A0101					Header type			537
SCHD3A0100								
SCHH1D0100				—	Adapter	—	539	

Note

○marks in "Available for automotive use" indicate that some of the series products can work at the operating temperature range from -40°C to +85°C.

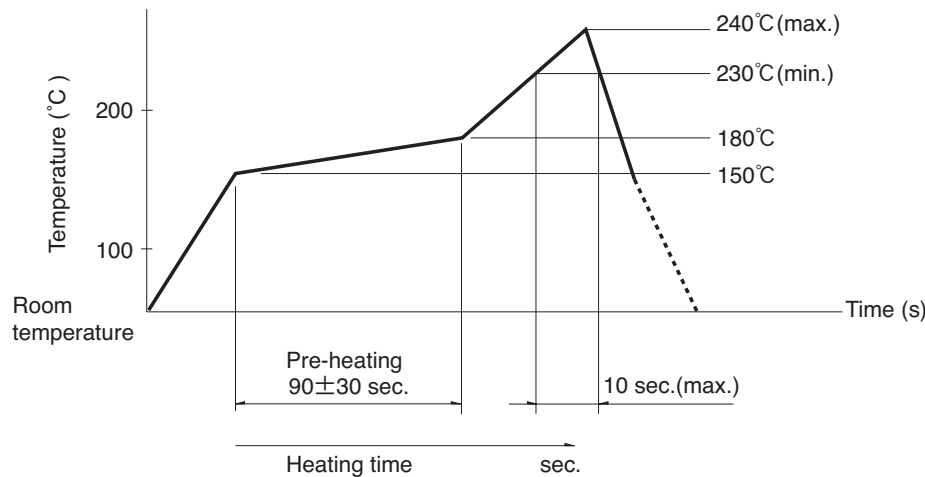
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Soldering Conditions

Example of Reflow Soldering Condition (Reference)

1. Heating method: Double heating method with infrared heater.
2. Temperature measurement: Thermocouple 0.1 to 0.2 ϕ CA (K) or CC (T) at soldering portion.
3. Temperature profile



For
SD Memory
Card

For
microSD™
Card

For
SIM Card
8pins

For
Memory
Stick Micro™

Combine Type

For
W-SIM

Please refer to each product's specification sheet to confirm temperature profile.

Cautions for using this product

1.Connector handling precautions

- (1) Safeguard the connector assembly against flux penetration from its top side.
- (2) This product is designed on the assumption that they will not be washed after soldering.

If you wash it, it may cause deterioration of mechanically and electrically.

If washing is necessary, please make contact with us beforehand.

2.When soldering terminals, there is a danger that load placed on the terminals may cause rattle, deformation or electrical degradation to occur depending on the conditions.

Caution is therefore required.

3.When soldering, do not use water soluble flux because this may corrode the product.

4.regarding the setting of reflow conditions, please confirm them with the actual mass production conditions.

5.As P.W.B. warping may alter characteristics, please take this into consideration when designing pattern and layout.

6.Please do not solder at the ejector pushing position.

7.To prevent contact disturbance by the sulfuration or oxidation of the contact and terminal, and deterioration of solder ability by thin film on the terminal, please note following.

- Storage in the atmosphere of high temperature at 60 degrees or more, high humidity, corrosive gases such as sulfur or chlorine gas, and excessive piling up of the carton boxes shall be avoided.
- Connectors shall be stored as the package not opened and in the normal temperature and normal humidity, and the connectors shall be used preferably within 3 months, at least within 6 months.
- When the connectors are stored after opening the package, the connectors shall be sealed with a polyethylene bag etc. and stored in dark and cool place, avoiding direct sunlight. Bag etc. and stored in dark and cool place, avoiding direct sunlight. The connectors shall be used as soon as possible.

8.Don't push or hold down the metal cover of the connector, otherwise there is a possibility that the card would not be ejected or influences to other function.

9.Please attention following items to prevent connector from miss operation, such as bounding caused by ON/OFF switching and chattering by vibration.

- Repeated reading/writing.
- Establish delay time-recommended 400msec min.
- Establish CR accumulation circuit.

10.This product does not operate normally when the card which does not conform to the specification is used occasionally.